

10822193_CLS.txt
Most Frequently Occurring Classifications of Patents Returned
From A Search of 10822193 on March 13, 2006

Original Classifications

3 324/158.1
3 430/30
3 438/14
2 174/68.1
2 257/48
2 324/763
2 324/765
2 326/16
2 360/137
2 430/5

Cross-Reference Classifications

3 324/765
3 438/18
2 74/483PB
2 204/192.15
2 250/491.1
2 250/559.37
2 250/559.38
2 257/48
2 257/E21.314
2 257/E23.145
2 326/39
2 326/44
2 355/53
2 356/401
2 358/406
2 360/69
2 360/74.1
2 377/129
2 377/72
2 430/22
2 438/622
2 700/121
2 714/725
2 716/4

Combined Classifications

5 324/765
4 257/48
4 324/158.1
4 430/30
4 438/14
3 324/763
3 355/53
3 358/406
3 430/5
3 438/18
2 73/45.4
2 74/483PB
2 174/68.1
2 204/192.15
2 250/491.1
2 250/559.37
2 250/559.38
2 257/758
2 257/797
2 257/E21.314

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2 257/E23.145
2 324/537
2 324/72.5
2 324/751
2 326/16
2 326/39
2 326/44
2 356/401
2 356/614
2 360/137
2 360/69
2 360/74.1
2 377/129
2 377/72
2 399/16
2 430/22
2 438/11
2 438/622
2 700/121
2 714/725
2 716/4

Titles of Most Frequently Occurring Classifications of Patents Returned
From A Search of 10822193 on March 13, 2006

- 5 324/765 (2 OR, 3 XR)
Class 324 : ELECTRICITY: MEASURING AND TESTING
324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
ELECTRIC COMPONENTS
324/537 .Of individual circuit component or element
324/765 ..Test of semiconductor device
- 4 257/48 (2 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/48 TEST OR CALIBRATION STRUCTURE
- 4 324/158.1 (3 OR, 1 XR)
Class 324 : ELECTRICITY: MEASURING AND TESTING
324/158.1 MISCELLANEOUS
- 4 430/30 (3 OR, 1 XR)
Class 430 : RADIATION IMAGERY CHEMISTRY: PROCESS,
COMPOSITION, OR PRODUCT THEREOF
430/30 INCLUDING CONTROL FEATURE RESPONSIVE TO A TEST
OR MEASUREMENT
- 4 438/14 (3 OR, 1 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/14 WITH MEASURING OR TESTING
- 3 324/763 (2 OR, 1 XR)
Class 324 : ELECTRICITY: MEASURING AND TESTING
324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
ELECTRIC COMPONENTS
324/537 .Of individual circuit component or element
324/763 ..DUT including test circuit
- 3 355/53 (1 OR, 2 XR)
Class 355 : PHOTOCOPYING
355/18 PROJECTION PRINTING AND COPYING CAMERAS
355/53 .Step and repeat
- 3 358/406 (1 OR, 2 XR)
Class 358 : FACSIMILE AND STATIC PRESENTATION PROCESSING
358/400 FACSIMILE
358/406 .Facsimile measuring, testing, or calibrating
- 3 430/5 (2 OR, 1 XR)
Class 430 : RADIATION IMAGERY CHEMISTRY: PROCESS,
COMPOSITION, OR PRODUCT THEREOF
430/4 RADIATION MODIFYING PRODUCT OR PROCESS OF
MAKING
430/5 .Radiation mask
- 3 438/18 (0 OR, 3 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/14 WITH MEASURING OR TESTING
438/17 .Electrical characteristic sensed
438/18 ..Utilizing integral test element

2 257/E21.314 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE

OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE

DEVICES OR OF

PARTS THEREOF (EPO)

257/E21.002 .Manufacture or treatment of semiconductor device (EPO)

257/E21.04 ..Device having at least one potential-jump barrier or surface barrier, e.g., PN junction,

depletion

257/E21.085 ...Device having semiconductor body comprising layer, carrier concentration layer (EPO)

without Group IV elements or Group III-V compounds with or

257/E21.211Treatment of semiconductor body using impurities, e.g., doping materials (EPO)

material on process other than deposition of semiconductor

material, or a substrate, diffusion or alloying of impurity

257/E21.214To change their surface-physical radiation treatment (EPO)

cutting characteristics or shape, e.g., etching, polishing,

257/E21.294Deposition/post-treatment of (EPO)

layers on noninsulating, e.g., conductive - or resistive -

257/E21.3Post treatment (EPO)

257/E21.305Physical or chemical etching of layer, e.g., to produce a patterned layer from pre-deposited extensive layer (EPO)

257/E21.314Using mask (EPO)

2 257/E23.145 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.139 ...Liquid at normal operating temperature of device (EPO)

257/E23.141 .Arrangements for conducting electric current within device in operation from one component to

another,

257/E23.142 ..Including external interconnections, e.g., wires, lead frames (EPO)

body consisting of multilayer structure of conductive and insulating layers inseparably formed on semiconductor

257/E23.145 ...Via connections in multilevel (EPO)

interconnection structure (EPO)

2 324/537 (1 OR, 1 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF ELECTRIC COMPONENTS

324/537 .Of individual circuit component or element

2 324/72.5 (1 OR, 1 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/72 TESTING POTENTIAL IN SPECIFIC ENVIRONMENT (E.G., LIGHTNING STROKE)

324/72.5 .voltage probe

- 2 324/751 (1 OR, 1 XR)
 Class 324 : ELECTRICITY: MEASURING AND TESTING
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF
 ELECTRIC COMPONENTS
 324/537 .Of individual circuit component or element
 324/750 ..System sensing fields adjacent device under
 test (DUT)
 324/751 ...Using electron beam probe
- 2 326/16 (2 OR, 0 XR)
 Class 326 : ELECTRONIC DIGITAL LOGIC CIRCUITRY
 326/16 WITH TEST FACILITATING FEATURE
- 2 326/39 (0 OR, 2 XR)
 Class 326 : ELECTRONIC DIGITAL LOGIC CIRCUITRY
 326/37 MULTIFUNCTIONAL OR PROGRAMMABLE (E.G.,
 UNIVERSAL, ETC.)
 326/39 .Array (e.g., PLA, PAL, PLD, etc.)
- 2 326/44 (0 OR, 2 XR)
 Class 326 : ELECTRONIC DIGITAL LOGIC CIRCUITRY
 326/37 MULTIFUNCTIONAL OR PROGRAMMABLE (E.G.,
 UNIVERSAL, ETC.)
 326/39 .Array (e.g., PLA, PAL, PLD, etc.)
 326/44 ..Field effect transistor
- 2 356/401 (0 OR, 2 XR)
 Class 356 : OPTICS: MEASURING AND TESTING
 356/399 BY ALIGNMENT IN LATERAL DIRECTION
 356/401 .With registration indicia (e.g., scale)
- 2 356/614 (1 OR, 1 XR)
 Class 356 : OPTICS: MEASURING AND TESTING
 356/614 POSITION OR DISPLACEMENT
- 2 360/137 (2 OR, 0 XR)
 Class 360 : DYNAMIC MAGNETIC INFORMATION STORAGE OR
 RETRIEVAL
 360/137 MISCELLANEOUS
- 2 360/69 (0 OR, 2 XR)
 Class 360 : DYNAMIC MAGNETIC INFORMATION STORAGE OR
 RETRIEVAL
 360/69 AUTOMATIC CONTROL OF A RECORDER MECHANISM
- 2 360/74.1 (0 OR, 2 XR)
 Class 360 : DYNAMIC MAGNETIC INFORMATION STORAGE OR
 RETRIEVAL
 360/69 AUTOMATIC CONTROL OF A RECORDER MECHANISM
 360/71 .Controlling the record
 360/74.1 / ..Stopping or reversing
- 2 377/129 (0 OR, 2 XR)
 Class 377 : ELECTRICAL PULSE COUNTERS, PULSE DIVIDERS, OR
 SHIFT REGISTERS: CIRCUITS AND SYSTEMS
 377/129 PULSES CONTINUOUSLY CIRCULATED IN A CLOSED LOOP
- 2 377/72 (0 OR, 2 XR)
 Class 377 : ELECTRICAL PULSE COUNTERS, PULSE DIVIDERS, OR
 SHIFT REGISTERS: CIRCUITS AND SYSTEMS
 377/64 SHIFT REGISTER

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377/70	.Particular input circuit
377/72	..With feedback
2 399/16	(1 OR, 1 XR)
Class 399	: ELECTROPHOTOGRAPHY
399/9	DIAGNOSTICS
399/16	.Document handling
2 430/22	(0 OR, 2 XR)
Class 430	: RADIATION IMAGERY CHEMISTRY: PROCESS,
	COMPOSITION, OR PRODUCT THEREOF
430/22	REGISTRATION OR LAYOUT PROCESS OTHER THAN COLOR
	PROOFING
2 438/11	(1 OR, 1 XR)
Class 438	: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/5	INCLUDING CONTROL RESPONSIVE TO SENSED
	CONDITION
438/10	.Electrical characteristic sensed
438/11	..Utilizing integral test element
2 438/622	(0 OR, 2 XR)
Class 438	: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
438/584	COATING WITH ELECTRICALLY OR THERMALLY
	CONDUCTIVE MATERIAL
438/597	.To form ohmic contact to semiconductive
	material
438/618	..Contacting multiple semiconductive regions
	(i.e., interconnects)
438/622	...Multiple metal levels, separated by
	insulating layer (i.e., multiple level metallization)
2 700/121	(0 OR, 2 XR)
Class 700	: DATA PROCESSING: GENERIC CONTROL SYSTEMS OR
	SPECIFIC APPLICATIONS
700/90	SPECIFIC APPLICATION, APPARATUS OR PROCESS
700/95	.Product assembly or manufacturing
700/117	..Particular manufactured product or operation
700/121	...Integrated circuit production or
	semiconductor fabrication
2 714/725	(0 OR, 2 XR)
Class 714	: ERROR DETECTION/CORRECTION AND FAULT
	DETECTION/RECOVERY
714/699	PULSE OR DATA ERROR HANDLING
714/724	.Digital logic testing
714/725	..Programmable logic array (PLA) testing
2 716/4	(0 OR, 2 XR)
Class 716	: DATA PROCESSING: DESIGN AND ANALYSIS OF
	CIRCUIT OR SEMICONDUCTOR MASK
716/1	CIRCUIT DESIGN
716/4	.Testing or evaluating